

CLAIMS

1. Microminiature image pickup device

that is a microminiature image pickup device that has an image pickup element, optical glass furnished on the front surface of said image pickup element, a stacked circuit board that is furnished on the rear surface of said image pickup element and that has a wiring pattern, and a connection member that electrically connects said image pickup element and the wiring pattern of said stacked circuit board;

said stacked circuit board is formed with insulated circuit boards, in which are packaged electronic circuits that include wiring patterns, stacked in multiple layers in the diametral direction perpendicular to the length direction of the microminiature image pickup device and it has a cavity formed as an indentation in the diametral direction thereof;

a first electronic component is mounted in said cavity, and a second electronic component is mounted on the surface of said stacked circuit board.

2. Microminiature image pickup device described in Claim 1

where said first electronic instrument is connected to a wiring pattern formed on the bottom surface of said cavity.

3. Microminiature image pickup device described in Claim 1 or 2 where said first electronic component is mounted in said cavity in a bare chip state.

4. Microminiature image pickup device described in Claim 1, 2, or 3 where said image pickup device is a CCD device.

5. Microminiature image pickup device described in Claim 1, 2, 3, or 4 where said connection member is TAB tape.